



### FEATURES

- ✧ Solid-state silicon-avalanche technology
- ✧ Array of surge rated diodes with internal TVS diode
- ✧ Low capacitance for high-speed interfaces
- ✧ Low leakage current and clamping voltage
- ✧ Low operating voltage
- ✧ RoHS compliant

### MAIN APPLICATIONS

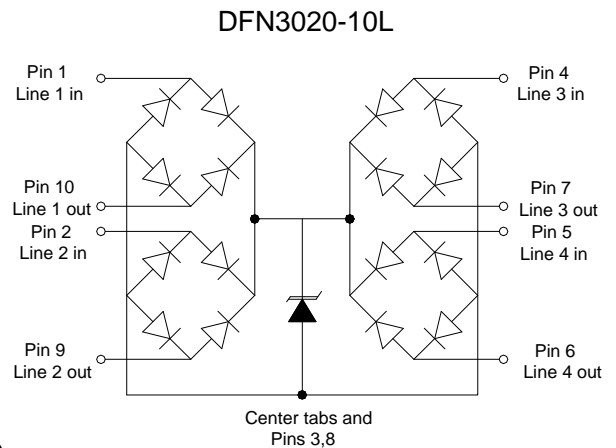
- ✧ 10/100/1000 ethernet
- ✧ Digital visual interface
- ✧ Analog video

### PROTECTION SOLUTION TO MEET

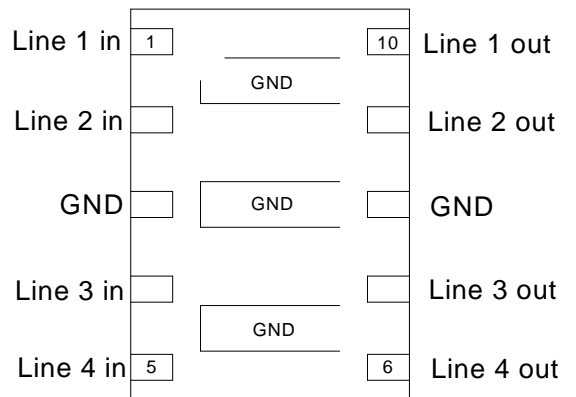
- ✧ IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ IEC61000-4-5 (Lightning) 40A (8/20μs)(Line to line)

### MECHANICAL CHARACTERISTICS

- ✧ DFN3020-10L package
- ✧ Molding compound flammability rating: UL 94V-0
- ✧ Quantity per reel: 3,000pcs
- ✧ Lead finish: lead free
- ✧ Marking code: 220425+Data code



Circuit Diagram



**ABSOLUTE MAXIMUM RATINGS** (T<sub>A</sub>=25 , RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20 s waveform	P <sub>PP</sub>	1000	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	+/-30 +/-30	kV
Lead soldering temperature	T <sub>L</sub>	260 (10 sec.)	
Operating junction temperature range	T <sub>J</sub>	-55 to +125	
Storage temperature range	T <sub>STG</sub>	-55 to +150	

**ELECTRICAL CHARACTERISTICS** (T<sub>A</sub>=25 )

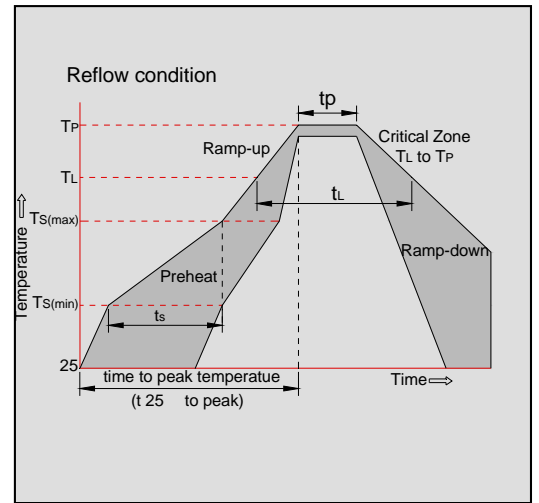
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V <sub>RWM</sub>	I/O to GND			2.5	V
Reverse leakage current	I <sub>R</sub>	I/O to GND @ V <sub>RWM</sub> =2.5V		0.1	1.0	A
Trigger voltage	V <sub>t1</sub>	I <sub>t1</sub> =1 A	3.0			V
Holding voltage	V <sub>h</sub>	I <sub>h</sub> =1mA	3.0			V
Clamping voltage	V <sub>C</sub>	I <sub>PP</sub> =1A, t <sub>P</sub> =8/20 s I/O to GND		6	8	V
		I <sub>PP</sub> =10A, t <sub>P</sub> =8/20 s I/O to GND		9	11	V
		I <sub>PP</sub> =25A, t <sub>P</sub> =8/20 s I/O to GND		13	15	V
		I <sub>PP</sub> =40A, t <sub>P</sub> =8/20 s Line to line, two I/O pins connected together on each line(Note 1)		20	22	V
Junction capacitance	C <sub>J</sub>	V <sub>RWM</sub> =0V, f=1MHz I/O pin to GND		3.5	4.0	pF
		V <sub>RWM</sub> =0V, f=1MHz Between I/O pins		1.5	2.0	pF

1 ) Ratings with 2 pins connected together per recommended configuration(ie pin 1 connected to pin 10, pin 2 connected to pin 9, pin 4 connected to pin 7, and pin 5 connected to pin 6.)

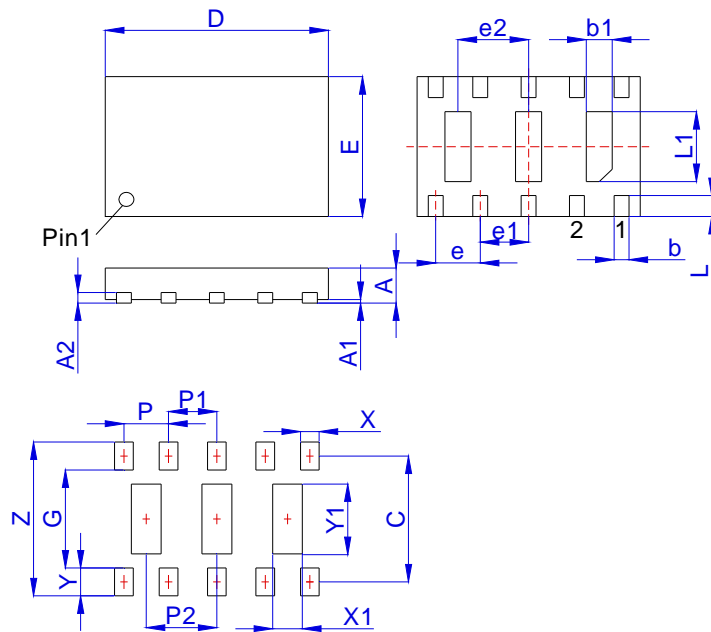


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150
	-Temperature Max( $T_{s(max)}$ )	+200
	-Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3 /sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3 /sec. Max
Reflow	-Temperature( $T_L$ )(Liquidus)	+217
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)
Time within 5 of actual Peak Temp ( $t_p$ )		20-40secs.
Ramp-down Rate		6 /sec. Max
Time 25 to Peak Temp ( $T_p$ )		8 min. Max
Do not exceed		+260



PACKAGE MECHANICAL DATA



Land Pattern

Symbol	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D	2.95	3.00	3.05	0.116	0.118	0.120
E	1.95	2.00	2.05	0.077	0.079	0.081

**ORDERING INFORMATION**

Part Number	Package	Quantity Per Reel (PCS)	Reel Size
JEU2574N	DFN3020-10L	3,000	7 Inch

**APPLICATION INFORMATION**

Electronic equipment is susceptible to damage caused by a variety of sources, including electrostatic discharge (ESD), electrical fast transients (EFT) and lightning strikes. The JEU2574N was designed to protect the sensitive equipment from damage which may be induced by such transient events. This product can be configured in different connections to meet the requies. The JEU2574N meet t9(t)1.4mmon-mod.0057 h

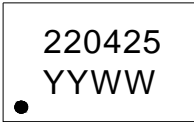
Gigabit ethernet protection(Cont.)

Schematic diagram for gigabit ethernet ESD/surge protection using JEU2574N

NOTE:

Please connect pin3, Pin8 and all GND tabs of JEU2574N to the ground plane of the systems.

MARKING CODE

Part Number	Marking Code
JEU2574N	
	220425:Marking Code YYWW: Date Code

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